

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Reissue Application of

PAI-HSIANG KAO, et al.

Patent No. 6,023,094

Issued: February 8, 2000

For: **SEMICONDUCTOR WAFER HAVING
A BOTTOM SURFACE PROTECTIVE
COATING**

**STATEMENT REGARDING
CLAIMS PURSUANT TO 37
CFR§1.173(C)**

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Box Reissue
Commissioner for Patents
Washington, D.C. 20231

Claim Status

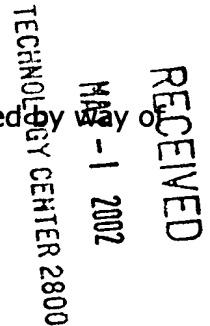
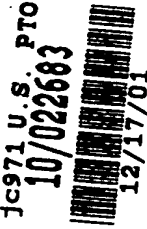
The status of the claims of the subject reissue application, as amended by way of the accompanying Preliminary Amendment, is as follows:

Claim 1 has been amended.

New Claims 7 – 15 have been added.

Support for Changes in Claims

Reference is made to the column (Col.) and line numbers (Lines) and the drawings (Fig.) of USPN. 6,023,094



Amended Claim 1

--contact bumps--

--opposite the first surface--

Support

"Bumps 106 are formed in the electrical contacts..." Col. 4, Lines 2-3

The bottom surface 104 and top surface 108 are on opposite sides of the die. See, Col. 4, Lines 2-3.

New Claim 7

--the protective film includes plastic--

Support

See, Col. 4, lines 8-9.

New Claim 8

--the protective film includes epoxy--

Support

See, Col. 4, lines 8-9.

New Claim 9

--the protective film includes laser identification markings--

Support

See, Col. 5, lines 61-62.

New Claim 10

--the protective film is non-metallic--

Support

plastic and epoxy (See, Col. 4, lines 7-9) are non-metallic.

New Claim 11

Claim 11 is rewritten original patent Claim 1 with the added language:

Support

--opposite the first surface-- and

The bottom surface 104 and top surface 108 are on opposite sides of the die. See, Col. 4, Lines 2-3.

--laser identification markings--

See, Col. 5, lines 61-62.

New Claim 12

--the protective film includes
epoxy--

Support

See, Col. 4, Lines 8-9.

New Claim 13

--the protective film includes
plastic--

Support

See, Col. 4, Lines 8-9.

New Claim 14

--the protective film is substantially
co-extensive with the back surface--

Support

See, Fig. 2 of drawings

New Claim 15

--plurality of contact bumps--

Support

See, Col. 4, Lines 2-3.

Respectfully submitted,

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Dated: 11/15/01

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